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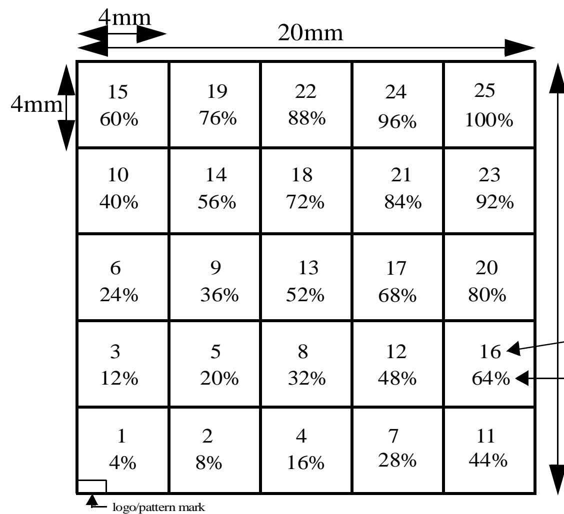
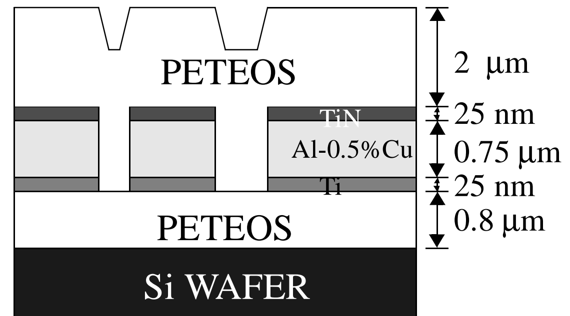
SKW1 200mm Wafer Specifications

DATE: November 30, 2001





SKW1 Density Mask Floor Plan & Cross Section View

PARAMETER	NOMINAL	TOLERANCE
Patterning		
Center Die X Location	-10.000 mm	+/- 100 µm
Center Die Y Location	-10.000 mm	+/- 100 µm
Die Size: X	20 mm	+/- 10 µm
Die Size: Y	20 mm	+/- 10 µm
Die Spacing	120 µm	+/- 10 µm
Wafers must be patterned all the way to the edges of the wafer, i.e. no area anywhere on wafer unpatterned. (Under certain stepper operating conditions, 2mm or more edge exclusion is allowed.)		
Linewidth Variation (measured on 10 µm and 90 µm structures)		
Lot-to-Lot	10 µm, 90 µm	+/- 1 µm
Within-Lot (Wafer-to-Wafer)		+/- 1 µm
Within-Wafer		+/- 1 µm
Within-Die		+/- 1 µm
Thickness		
Lot-to-Lot	2.0 µm	+/- 5%
Within-Lot (Wafer-to-Wafer)		+/- 5%
Within-Wafer		+/- 2%
Within-Die		+/- 2%
Step-Height (Trench Depth)		
Lot-to-Lot	8000 Å	+/- 10%
Within-Lot (Wafer-to-Wafer)		+/- 10%
Within-Wafer		+/- 5%
Within-Die		+/- 5%